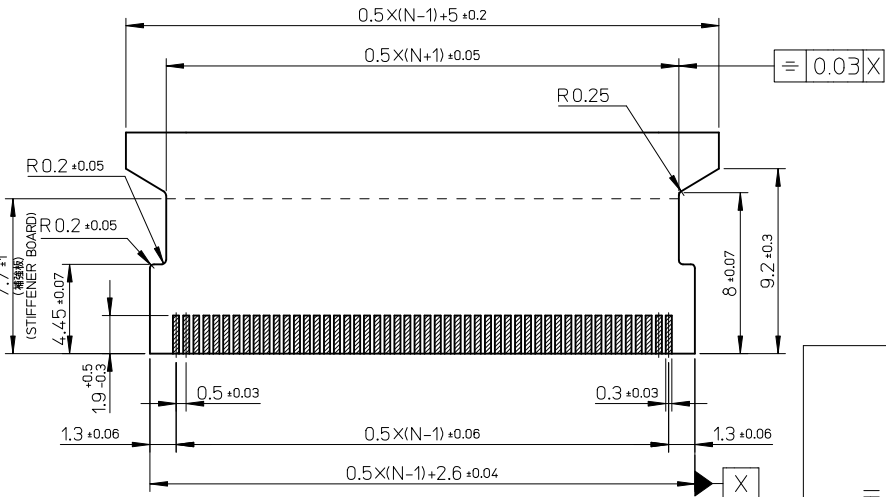
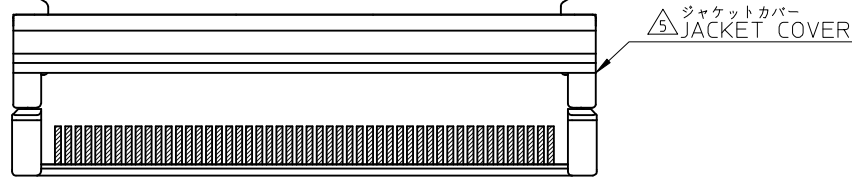
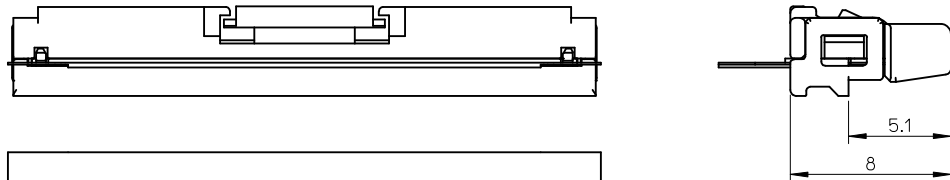
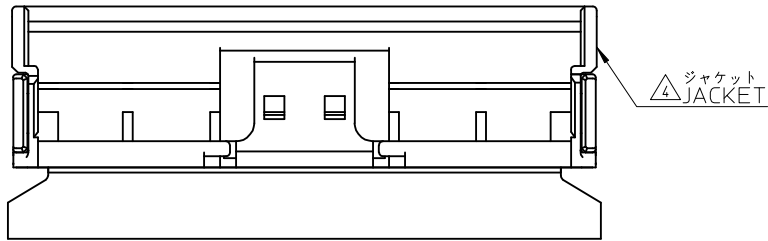


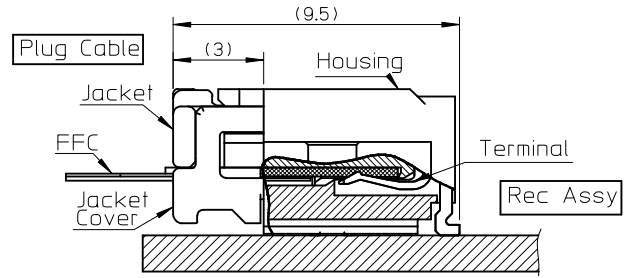
17.2	19.1	19.8	14.5	23.1	501864-3092	30
E	D	C	B	A	EMBOSSED TAPE PKG. ORDER No. オーダー番号	極数 CIRCUIT

REVISED EC NO: A	DESCRIPTION DRWN: NISHI CHKD: MATSUURA APPR: KMORIKAWA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE //	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY M. TAKASAKI	DATE 08/12/05	TITLE 0.5 FFC TO BOARD CONN REC. HSG ASSY(RA)			
		10 OVER 30 UNDER	± 0.25	CHECKED BY M. HAYASHI	DATE 08/12/05	MATERIAL NO. SEE CHART			
		30 OVER	± 0.3	APPROVED BY N. UKITA	DATE 08/12/05	DOCUMENT NO. SD-501864-012			
ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		SHEET NO. 1 OF 2			

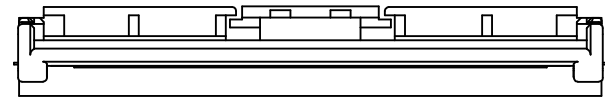


コネクタ接続部
CONTACT AREA

適合FFC寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 接続部 0.3 ± 0.03)
(THICKNESS : CONTACT AREA 0.3 ± 0.03)



嵌合断面図
MATED CONNECTOR SECTION



注記 1. 使用材料
NOTE MATERIAL

ハウジング
HOUSING
: 液晶ポリマー (LCP)・ガラス充填.
UL94V-0 色: 黒色
LIQUID CRYSTAL POLYMER(LCP)
GLASS FILLED UL94V-0 COLOR:BLACK

ターミナル
TERMINAL
: 銅合金 (τ=0.18)
COPPER ALLOY(τ=0.18)

メッキ
PLATING
コンタクト
CONTACT AREA
: ニッケル下地 金メッキ
GOLD OVER NICKEL PLATING

ソルダーテール
TAIL AREA
: ニッケル下地 金メッキ
GOLD OVER NICKEL PLATING

金具
FITTING NAIL
: 銅合金 (τ=0.25)
ニッケル下地 錫メッキ
COPPER ALLOY(τ=0.25)
TIN OVER NICKEL PLATING.

- △2 N=偶数に適用 (N:極数)
APPLY FOR N=EVEN(CIRCUIT)
- △3 パターン剥離止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B PATTERN.
- △4 適合ジャケット: 501783-**09
製品詳細寸法はSD-501783-004を参照下さい。
APPLICABLE JACKET:501783-**09.RE DETAILED DIMENSION.SEE SD-501783-004.
- △5 適合ジャケットカバー: 501784-**09
製品詳細寸法はSD-501784-004を参照下さい。
APPLICABLE JACKET:501784-**09.RE DETAILED DIMENSION.SEE SD-501784-004.

REVISED EC NO: A	DESCRIPTION DR:WANNISHI CHKD:WATSUURA APPR:KMORIKAWA	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE //	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY M. TAKASAKI	DATE 08/12/05	TITLE 0.5 FFC TO BOARD CONN REC. HSG ASSY(RA)			
		10 OVER 30 UNDER	± 0.25	CHECKED BY M. HAYASHI	DATE 08/12/05	MOLEX INCORPORATED			
		30 OVER	± 0.3	APPROVED BY N. UKITA	DATE 08/12/05	DOCUMENT NO. SD-501864-012			
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1		SHEET NO. 2 OF 2			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

10 9 8 7 6 5 4 3 2 1

F

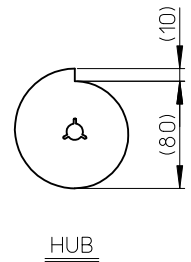
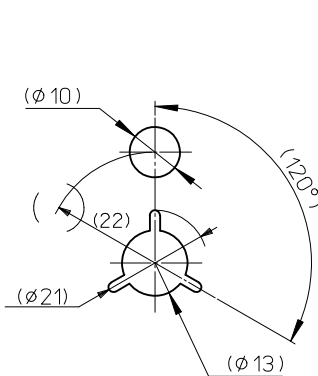
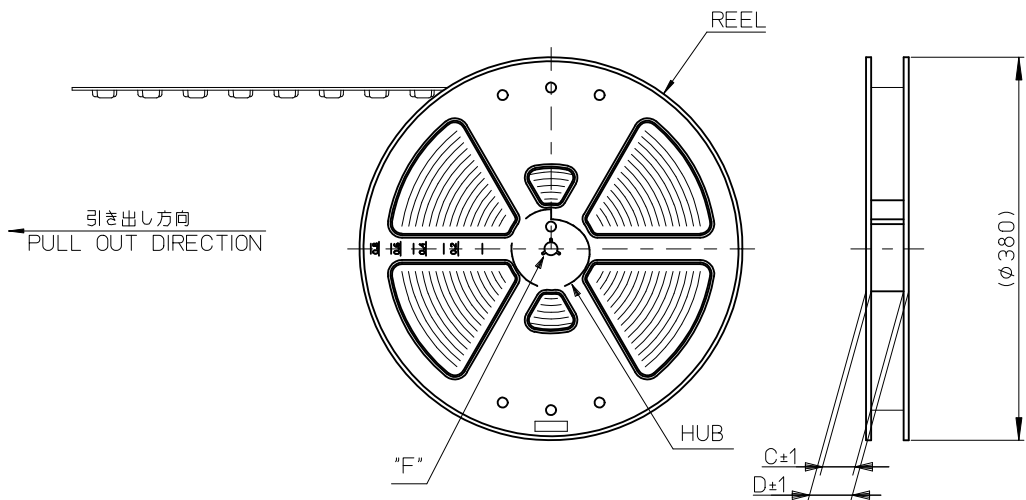
E

D

C

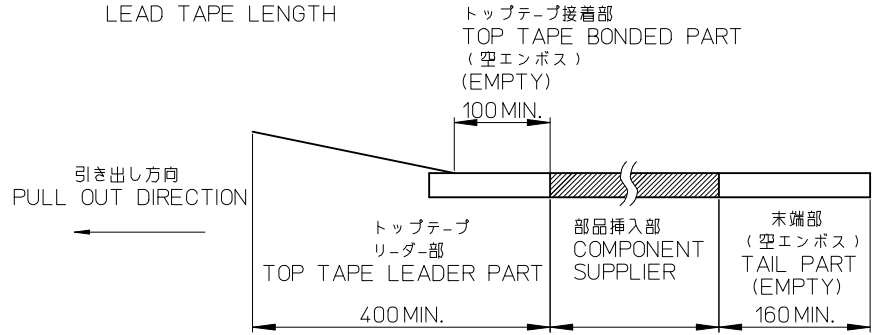
B

A



NOTES

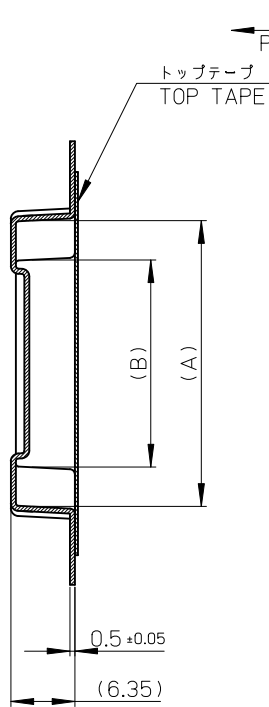
1. 梱包数量：900 個ノリール
NUMBER OF CONNECTORS:900 PCS/REEL
2. リードテープ長さ
LEAD TAPE LENGTH



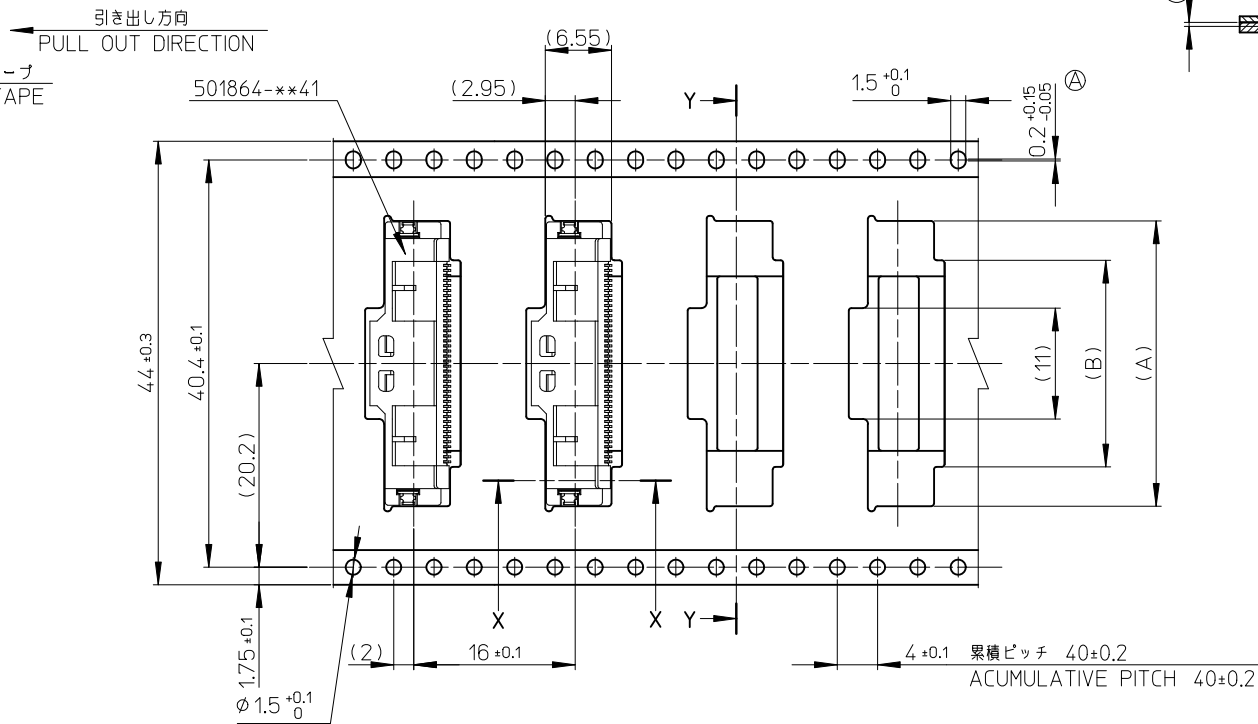
3. 製品詳細寸法については図面 SD-501864-012を参照下さい。
RE DETAILED DIMENSION, SEE SD-501864-012.
4. 材料(MATERIAL)
キャリアテープ(CARRIER TAPE)：ポリスチレン(POLYSTYRENE)
トップテープ(TOP TAPE)：PET, OTHER
リール(REEL)：ポリスチレン(POLYSTYRENE)

501864-**92 MODEL NO.

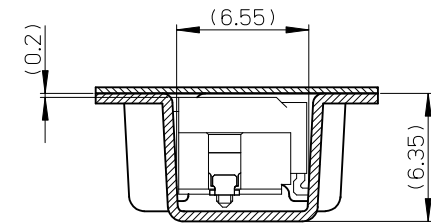
REVISED EC NO: J2012-0899 DRWN:KNAGUMO 2012/01/18 CHKD:KTAHASHI 2012/01/18 APPR:KMORIKAWA 2012/01/19	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	±0.2	DRAWN BY M. TAKASAKI	DATE 08/12/05	TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD CONN RA TYPE -LEAD FREE-				
		10 OVER 30 UNDER	±0.25	CHECKED BY M. HAYASHI	DATE 08/12/05	MOLEX INCORPORATED				
		30 OVER	±0.3	APPROVED BY N. UKITA	DATE 08/12/05					
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. 501864-**92		DOCUMENT NO. SD-501864-013		SHEET NO. 1 OF 2		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										



SECT. Y-Y



44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE



SECT. X-X

44	49.4	45.4	15.5	23.3	501864-3092	30
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	製品番号 MATERIAL NO.	極数 CKT

SEE SHEET 1 OF 2 EC NO.: J2012-0899 DRWN:KNAGUMO 2012/01/18 CHKD:KTAHASHI 2012/01/18 APPR:KMORIKAWA 2012/01/19	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY M. TAKASAKI	DATE 08/12/05	TITLE EMBSTP PKG FOR 0.5 FFC TO BOARD CONN RA TYPE -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY M. HAYASHI	DATE 08/12/05	MOLEX INCORPORATED MATERIAL NO. 501864-**92 DOCUMENT NO. SD-501864-013 SHEET NO. 2 OF 2		
	30 OVER	±0.3	APPROVED BY N. UKITA	DATE 08/12/05			
ANGULAR	±1°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					